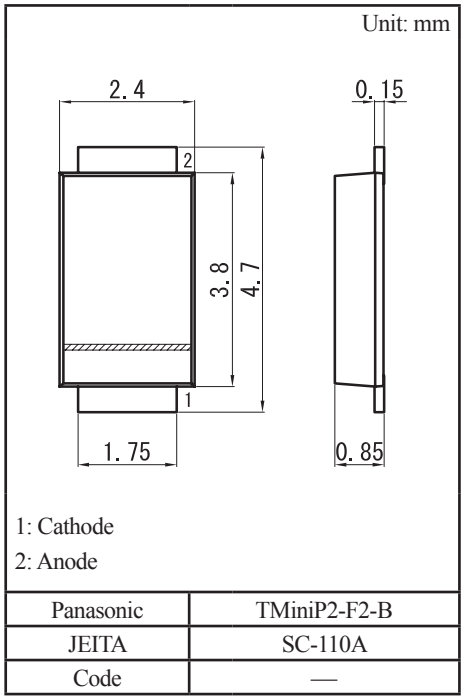
DZ24330

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit
Capability of withstanding a high surge type
DZ2W330 in Power type package



Panasonic	TMiniP2-F2-B
JEITA	SC-110A
Code	—

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: HG

■ Packaging

DZ2433000L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Forward current	I_F	400	mA
Repetitive peak forward current	I_{FRM}	500	mA
Total power dissipation *1	P_T	2	W
Non-repetitive reverse surge power dissipation *2	P_{ZSM}	100	W
Electrostatic discharge *3	ESD	±30	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

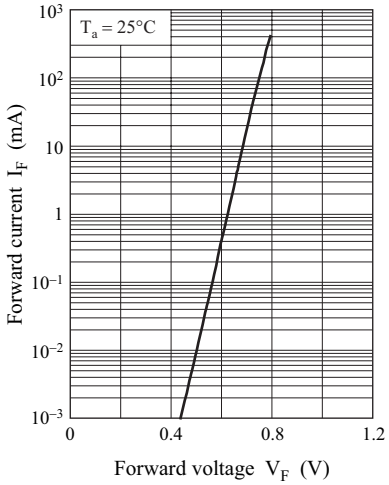
Note) *1: Mounted on ceramics print circuit board.
Board size: 50 mm × 50 mm, Board thickness: 0.8 mm, Soldering size: 2 mm × 2 mm
*2: t = 0.1 ms
*3: Test method:IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge:10 times)

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

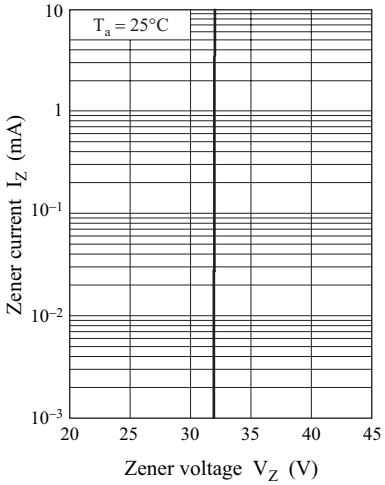
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA			1.2	V
Zener voltage *1, 2	V_Z	I_Z = 10 mA	31.35	33.00	34.65	V
Zener operating resistance	R_Z	I_Z = 10 mA			30	Ω
Reverse current	I_R	V_R = 26.4 V			10	μA
Temperature coefficient of zener voltage *3	S_Z	I_Z = 10 mA		34.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz.
3. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
*2: V_Z guaranteed 20 ms after current flow.
*3: T_j = 25°C to 150°C

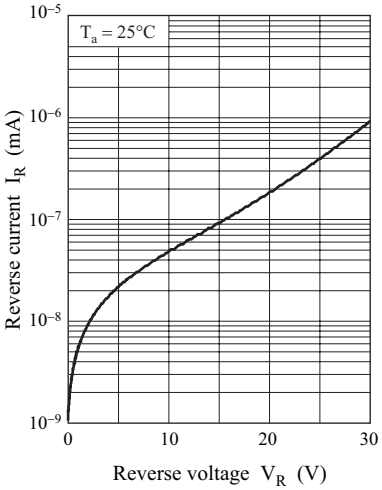
I_F — V_F



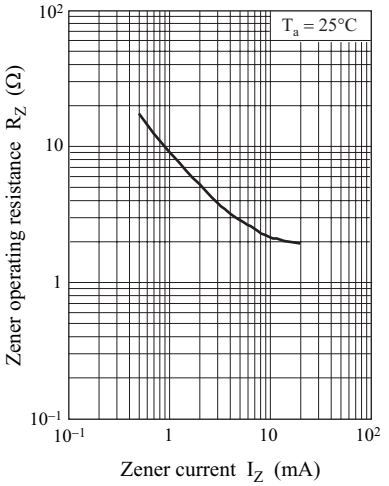
I_Z — V_Z



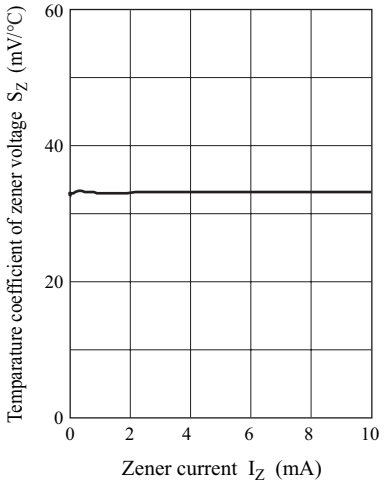
I_R — V_R



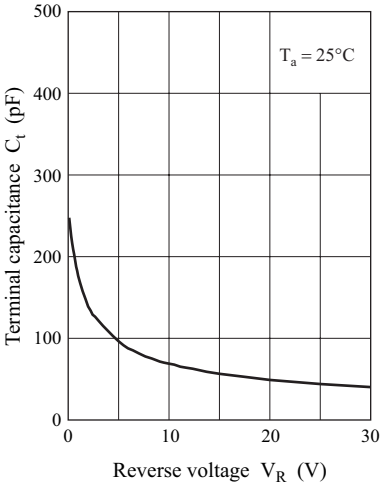
R_Z — I_Z



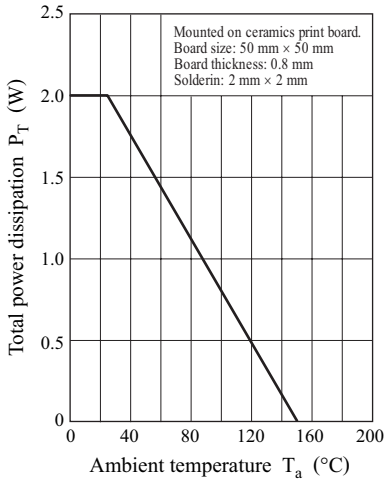
S_Z — I_Z



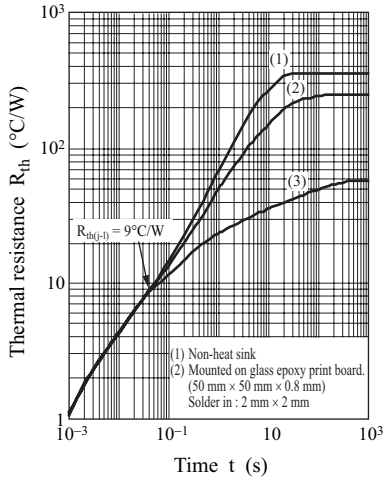
C_t — V_R



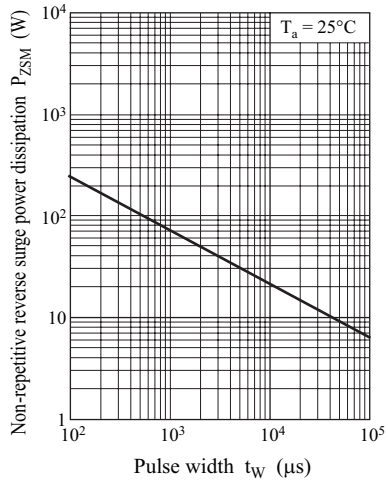
P_T — T_a



R_{th} — t

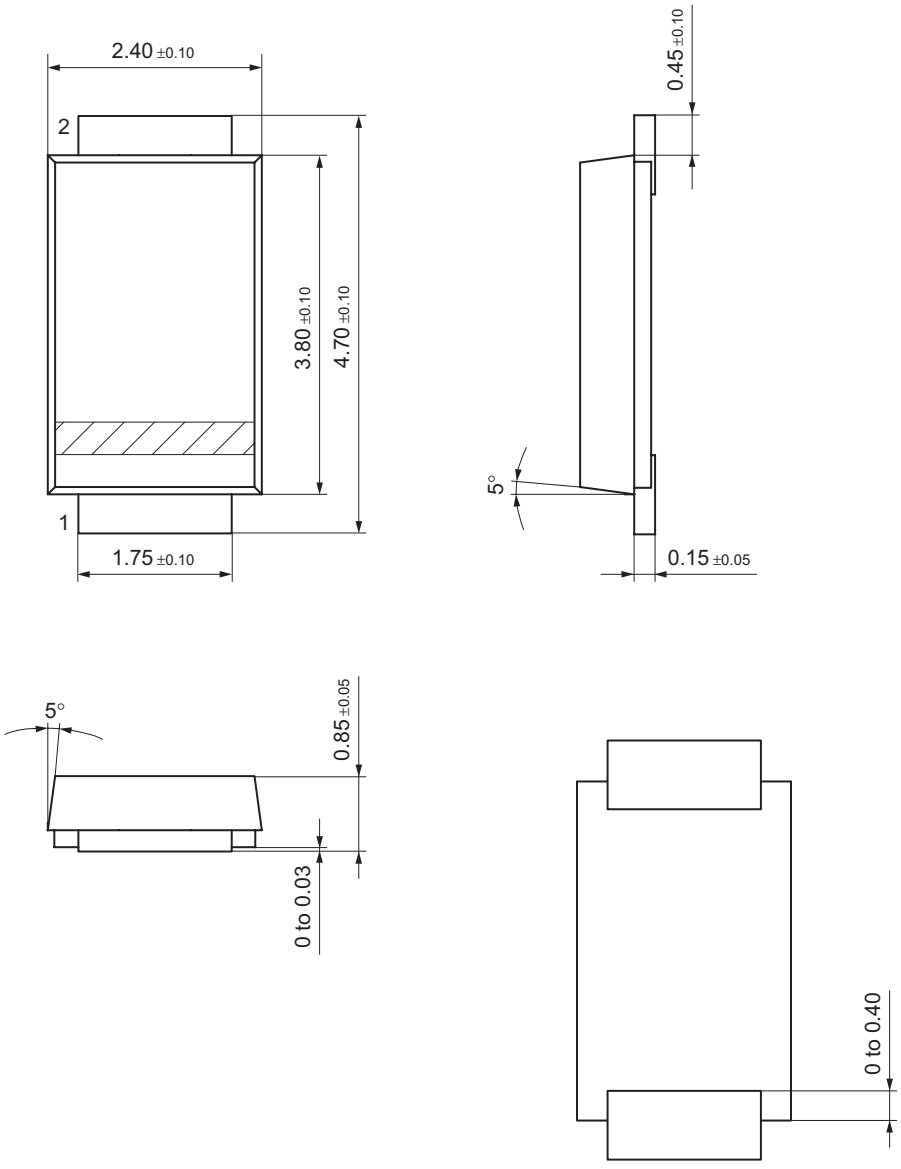


P_{ZSM} — t_W

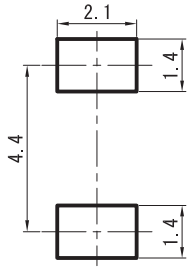


TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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